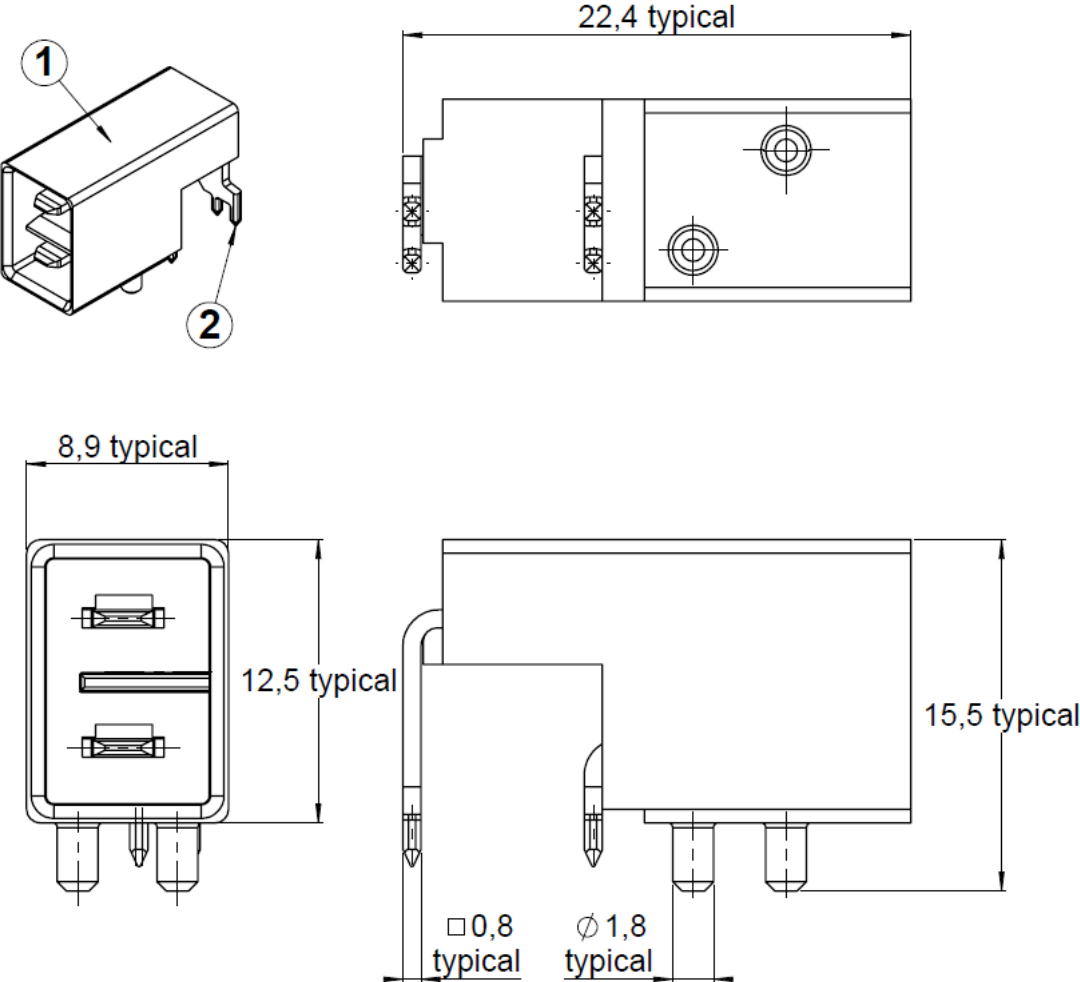


|          |                 |              |                        |
|----------|-----------------|--------------|------------------------|
| PAGE 1/5 | ISSUE 01-02-19A | SERIES OCTIS | PART NUMBER OCTI360500 |
|----------|-----------------|--------------|------------------------|



All dimensions are in mm. Tolerances according ISO 2768 m-H.

**DESCRIPTION**

| REP | COMPONENT | MATERIALS    | PLATING |
|-----|-----------|--------------|---------|
| 1   | Housing   | PLASTIC      | -       |
| 2   | Contact   | COPPER ALLOY | SN      |

PAGE 2/5

ISSUE **01-02-19A**

SERIES **OCTIS**

PART NUMBER **OCTI360500**

**GENERAL CHARACTERISTICS**

|                                                                                                                            |                                                |                                                                                                                                                                                                                                                                                       |
|----------------------------------------------------------------------------------------------------------------------------|------------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| <b>Mechanical</b><br>Mating endurance (cycles)<br>Vibration<br>Weight (g)                                                  | IEC 61300-2-2<br>EIA 364-28<br>-               | 100<br>-<br>1.1110                                                                                                                                                                                                                                                                    |
| <b>Environmental</b><br>Operating temperature (°C)<br>Storage temperature (°C)<br>RoHS<br>Flammability                     | IEC 61300-2-22<br>IEC 61300-2-22<br>-<br>UL 94 | -40 / +85<br>-65 / +85<br>Compliant<br>V0                                                                                                                                                                                                                                             |
| <b>Electrical</b><br>Working voltage<br>Current rating (A)<br><br>Dielectric withstanding voltage<br>Insulation resistance | -<br>-<br><br>EIA 364-20<br>EIA 364-21         | Max. 300V AC (r.m.s.)<br>16A in combination with 1.5mm <sup>2</sup> conductors (16AWG)<br>20A in combination with 2.5mm <sup>2</sup> (14AWG) & 3.3mm <sup>2</sup> conductors (12AWG)<br>500V AC<br>5000M $\Omega$ minimum initial<br>1000M $\Omega$ minimum after environmental aging |
| <b>Others</b><br>Packaging                                                                                                 | -                                              | Packaging in Tape&Reel (Quantity per reel to be defined)                                                                                                                                                                                                                              |

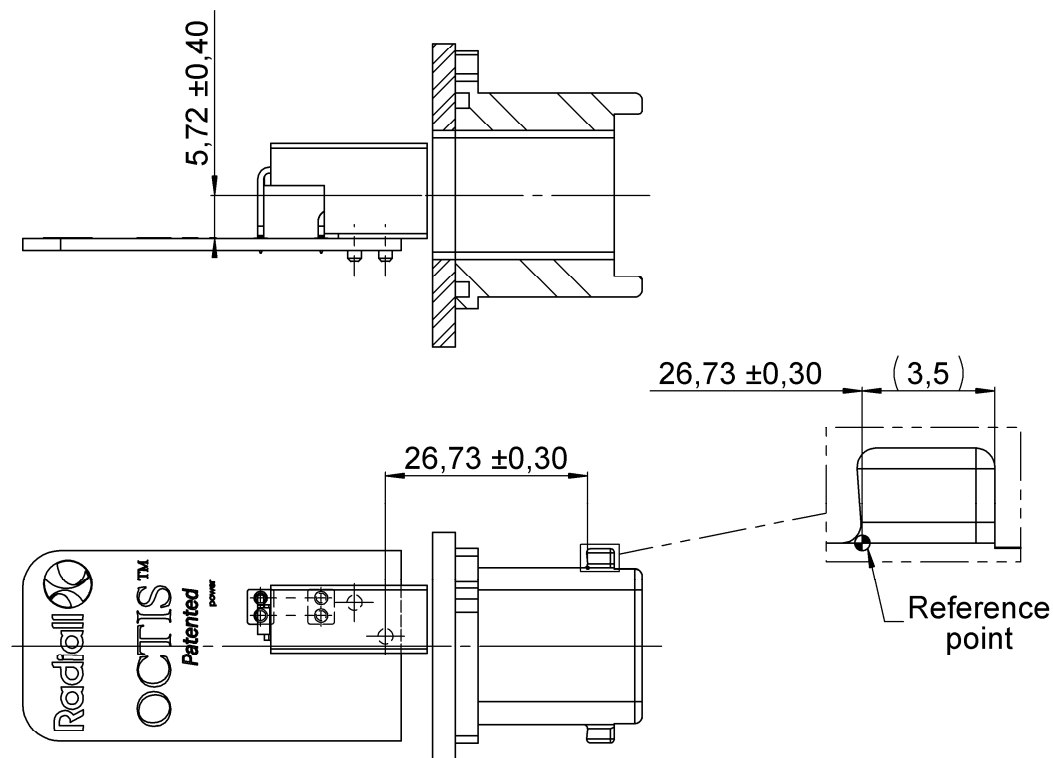
PAGE 3/5

ISSUE **01-02-19A**

SERIES **OCTIS**

PART NUMBER **OCTI360500**

**POSITIONING AND PATTERN DEFINITION**



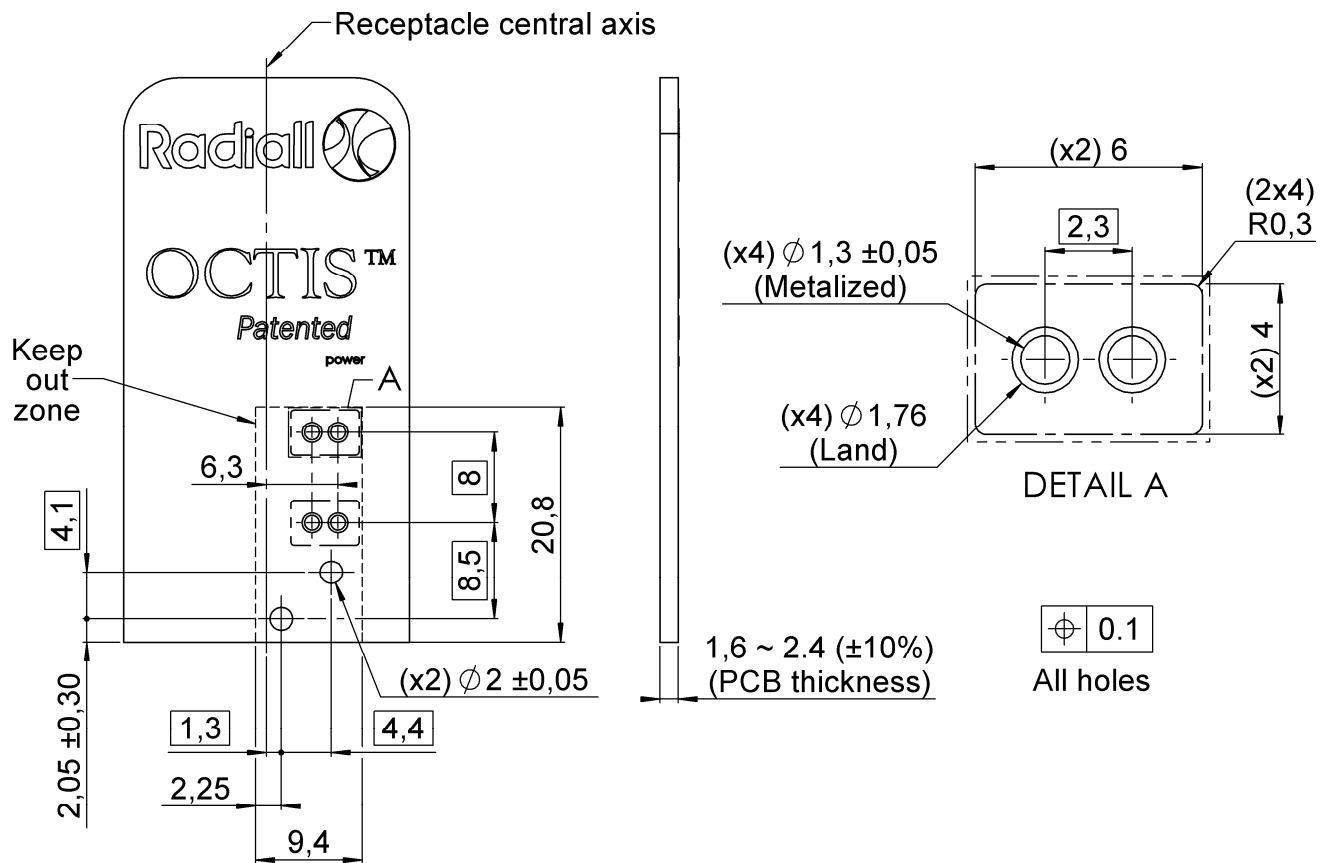
PAGE 4/5

ISSUE 01-02-19A

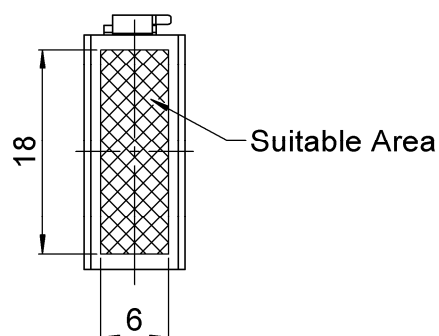
SERIES OCTIS

PART NUMBER OCTI360500

FOOT/PRINT (General tolerance for PCB  $\pm 0.1$  mm)



SUITABLE AREA FOR PICK & PLACE VACUUM NOZZLE



PAGE 5/5

ISSUE **01-02-19A**

SERIES **OCTIS**

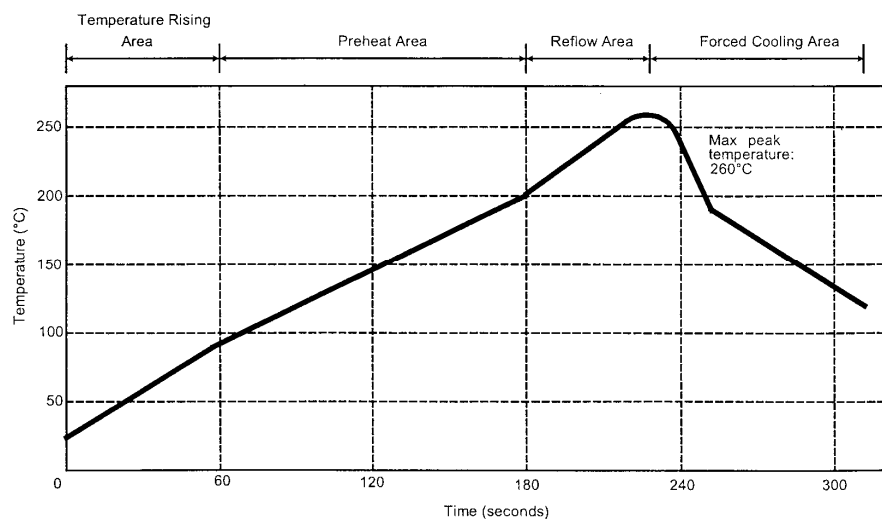
PART NUMBER **OCTI360500**

#### SOLDER PROCEDURE\*

1. Deposit solder paste (Sn Ag4 Cu0.5) on solder pads / mounting area by screen printing application. We recommend a low residue flux. Verify that the edges of the pads are clean.
2. Place the component on the mounting area with a pick & place machine. A video camera is recommended for a good positioning of the component. Adhesive agents must not be used on the component.
3. This process of soldering has been tested with a convection oven. Below please find the typical soldering profile to use.
4. Optional cleaning of printed circuit board.
5. Check solder joints and position of the component by visual inspection.

Note: When soldering a receptacle, no plug should be mated to the receptacle before completion of this procedure.

#### TEMPERATURE PROFILE



| Parameter                        | Value     | Unit   |
|----------------------------------|-----------|--------|
| Temperature rising Area          | 1 to 4    | °C/sec |
| Max Peak Temperature             | 260       | °C     |
| Max dwell time @260°C            | 10        | sec    |
| Min dwell time @235°C            | 20        | sec    |
| Max dwell time @235°C            | 60        | sec    |
| Temperature drop in cooling Area | -1 to - 4 | °C/sec |
| Max dwell time above 100°C       | 420       | sec    |

\* Typical data for reflow process. Alternatively, wave soldering is also possible